

Number of Components:	Two	Minimum Bond Line Cure Schedule*:	
Mix Ratio By Weight:	10:1	150°C	1 Minute
Specific Gravity:		120°C	5 Minutes
Part A	1.13	100°C	10 Minutes
Part B	1.02	80°C	30 Minutes
Pot Life:	3 Hours		
Shelf Life:	One year at room temperature.		

Note: Container(s) should be kept closed when not in use. *Please see Applications Note available on our website.
- TOTAL MASS SHOULD NOT EXCEED 25 GRAMS -

Product Description:

EPO-TEK[®] 353ND-T5 is an intermediate viscosity version of EPO-TEK[®] 353ND and EPO-TEK[®] 353ND-T. It was designed for high temperature applications in fiber optics, electronics and medical devices.

EPO-TEK[®] 353ND-T5 Advantages & Application Notes:

- Suggested applications:
 - Semiconductor, glob top DAM around IC's, using COB or DCA packaging formats
 - Electronics Assembly
 - Insulating adhesive for bonding stainless steel metals, ceramics and carbon composites used in ink-jetting heads
 - Insulating and plugging wires and feed-through cables of automotive circuits
 - Hard Disk Drive – thixotropic staking and termination of Al and Cu coils
 - Adhesive for brushless motors and Cu coil windings
 - Medical
 - Structural adhesive for endoscopes, camera optics and IR sensor devices
 - Optical
 - Fiber optic component packaging: bonding fibers, active optics, metals, ceramics and plastic
- Available in alternative viscosities and color. Contact techserv@epotek.com for your best recommendation.

Typical Properties: (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour; * denotes test on lot acceptance basis)

Physical Properties:	
*Color: Part A: Tan Part B: Amber	Die Shear Strength @ 23°C: ≥ 15 Kg / 5,100 psi
*Consistency: Smooth, slightly thixotropic paste	Degradation Temp. (TGA): 409°C
*Viscosity (@ 50 RPM/23°C): 4,000 – 7,000 cPs	Weight Loss:
Thixotropic Index: 2.1	@ 200°C: 0.53%
*Glass Transition Temp.(Tg): ≥ 90°C (Dynamic Cure	@ 250°C: 1.22%
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	@ 300°C: 2.37%
Coefficient of Thermal Expansion (CTE):	Operating Temp:
Below Tg: 43 x 10 ⁻⁶ in/in/°C	Continuous: - 55°C to 225°C
Above Tg: 231 x 10 ⁻⁶ in/in/°C	Intermittent: - 55°C to 325°C
Shore D Hardness: 80	Storage Modulus @ 23°C: 559,120 psi
Lap Shear Strength @ 23°C: 1,953 psi	*Particle Size: ≤ 20 microns
Electrical & Thermal Properties:	
Thermal Conductivity: N/A	Volume Resistivity: ≥ 4x10 ¹² Ohm-cm
Dielectric Constant (1 KHz): 3.21	Dissipation Factor (1 KHz): 0.003

EPOXY TECHNOLOGY, INC.
14 Fortune Drive, Billerica, MA 01821-3972 Phone: 978.667.3805 Fax: 978.663.9782
www.EPOTEK.com

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